



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Application No.: 09/856,627

Docket No.: 109609

Filed: May 24, 2001

For: INTERCONNECT SUBSTRATE, SEMICONDUCTOR DEVICE, METHODS OF FABRICATING, INSPECTING, AND MOUNTING THE SEMICONDUCTOR DEVICE, CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

REQUEST FOR CORRECTION OF PALM RECORDS

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Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,

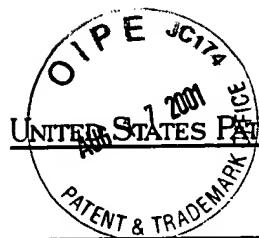
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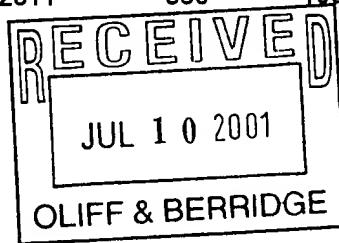


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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/856,627	05/24/2001	2811	860	109609	7	20	2-3



CONFIRMATION NO. 3172

FILING RECEIPT



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Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

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Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/JP00/06824 09/29/2000

Foreign Applications

JAPAN 11-281424(P) 10/01/1999

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Projected Publication Date: N/A

Non-Publication Request: No

Early Publication Request: No

Title

~~Wiring board, semiconductor device and method of producing, testing and packaging the same, and circuit board and electronic equipment~~

Preliminary Class

257

INTERCONNECT SUBSTRATE, SEMICONDUCTOR DEVICE, METHODS OF FABRICATING, INSPECTING, AND MOUNTING THE SEMICONDUCTOR DEVICE, CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT